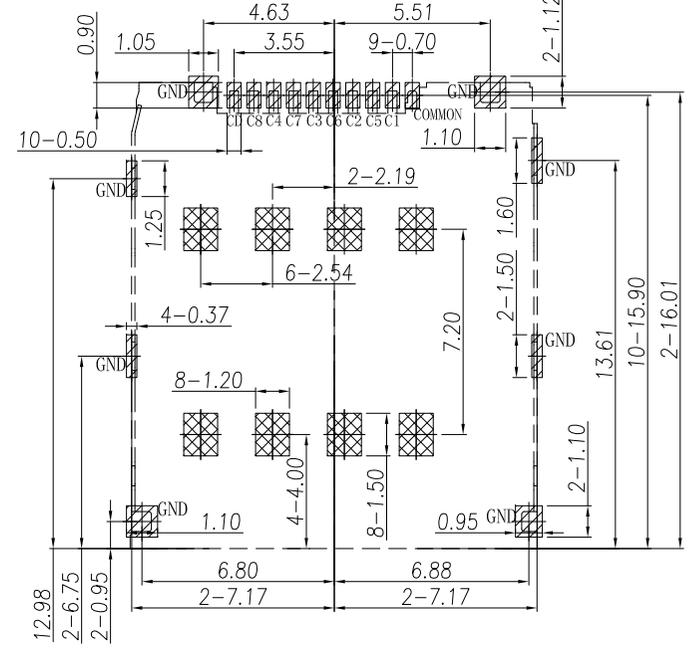
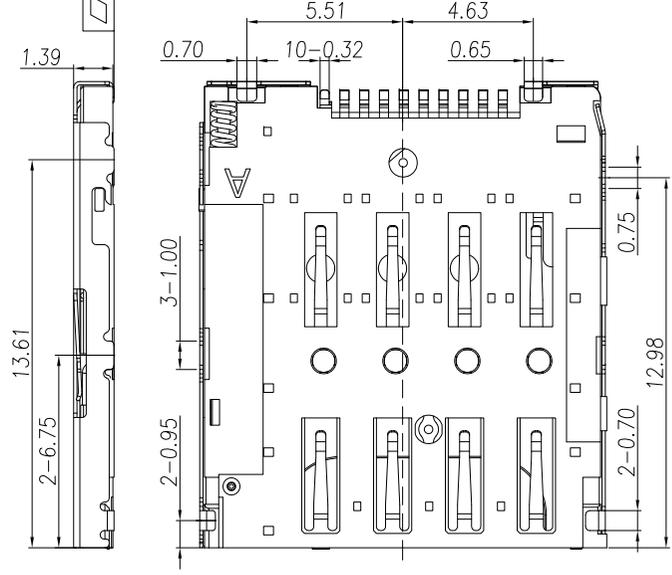
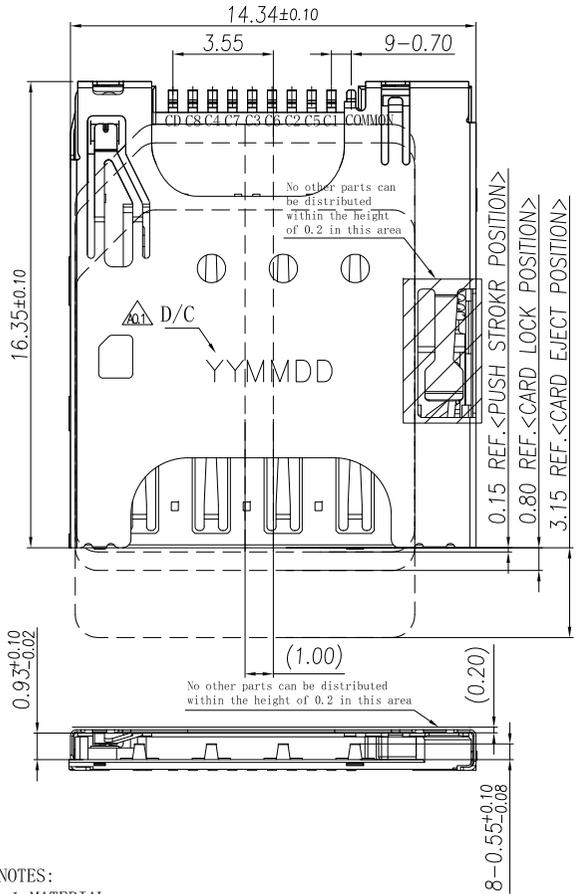


# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2022/06/14	Hanson
AO.1			Add D/C	2023/03/25	Hanson



MATRIX PART NO:  
**MSM-01-01-10-14-92**

Matrix Micro SIM Series Number  
 01 : Push Height  
 02 : Non-Push

Plating Pin number  
 01:G/F 10:10pin  
 05:5u  
 30:30u

RECOMMENDED PCB LAYOUT  
 TOLERANCE: ±0.05

▨ SMT SOLDER AREA  
 ▩ COPPER RESTRICTED AREA

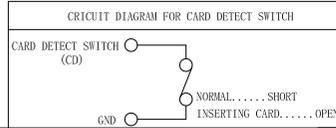
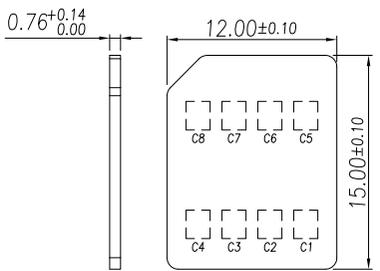
1. TOUCH AREA OF CONTACT  
 TIPS NO ELECTRICAL FUNCTION  
 2. NO FIRST PCB\_LAYOUT  
 CIRCUITS IN THE AREA

NOTES:

1. MATERIAL:  
 HOUSING: High Temperature Thermoplastic (LCP S475)  
 Terminal: Copper Alloy (C5210-EH)  
 Shell: Stainless Steel (SUS304-H)  
 Spring: Swp-B & Ni OVERALL

2. PLATING:  
 Terminal: 50u" Ni UNDERPLATED OVERALL  
 G/F PLATED ON CONTACT AREA  
 50u" Tin PLATED ON SOLDER AREA  
 Shell: 50u" Ni UNDERPLATED OVERALL  
 G/F PLATED ON SOLDER AREA

3. TECHNICAL SPECIALITY:  
 RATED VOLTAGE: 30V AC MAX.  
 CURRENT RATING: 0.5A MAX.  
 INSULATION RESISTANCE: 1000M Ω MIN  
 CONTACT RESISTANCE: 50m Ω MAX  
 WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES  
 OPERATING TEMPERATURE: -40°C~+85°C Humidity 80% R.H MAX



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED
CD	Detect Switch
COM	GND



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2023/03/25	PART NAME: Micro SIM card 1.40H
UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Vicky Hsieh	DATE : 2023/03/25	PART NO. MSM-01-01-10-14-92
	APPROVED BY1: Richard Hsieh	DATE : 2023/03/25	MOLD NO. NA
	APPROVED BY2: Richard Hsieh	DATE : 2023/03/25	DRAW NO. SHEET NO. 1 OF 1